Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in this application.

Please amend Claims 11 and 14-17.

Listing of Claims:

- 1. (withdrawn)
- 2. (withdrawn)
- 3. (withdrawn)
- 4. (withdrawn)
- 5. (withdrawn)
- 6. (withdrawn)
- 7. (withdrawn)
- 8. (withdrawn)
- 9. (withdrawn)
- 10. (withdrawn)
- 11. (currently amended and previously presented) A mandrel for use in fabricating <u>a</u> three dimensional electroformed <u>structures</u> <u>structure</u> comprising:
 - a substrate base;
- a <u>sacrificial</u> controlled-release layer applied to at least one surface of the substrate base; and
- a conductive metal layer applied to the eonductive-release sacrificial controlled-release layer wherein the conductive metal layer provides a surface upon which to electroform the structure an orifice plate forming the three dimensional electroformed structure, the substrate base provides rigidity to the mandrel, and the sacrificial controlled-release layer provides sufficient adhesion

to the substrate base to prevent the electroformed structure from delaminating from the substrate base during the electroforming processes and further provide a means to remove the electroformed structure from the substrate base without damage to either the electroformed structure or the substrate base.

- 12. (original) A mandrel as claimed in claim 11 wherein the substrate base comprises a metal substrate not attacked by chemicals used in electroforming processes.
- 13. (original) A mandrel as claimed in claim 11 wherein the substrate base comprises a chrome coated glass substrate.
- 14. (currently amended) A mandrel as claimed in claim 11 wherein the <u>sacrificial</u> controlled-release layer comprises an organic chemical layer.
- 15. (currently amended) A mandrel as claimed in claim 11 wherein the <u>sacrificial</u> controlled-release layer <u>further</u> comprises a controlled release layer whereby the electroformed substrate can be removed from the substrate base by chemically dissolving the controlled-release layer.
- 16. (currently amended) A mandrel as claimed in claim 11 wherein the <u>sacrificial</u> controlled-release layer comprises a controlled-release layer whereby the electroformed substrate can be removed from the substrate base by melting the controlled-release layer.
- 17. (currently amended) A mandrel as claimed in claim 11 wherein the <u>sacrificial</u> controlled-release layer comprises a brittle controlled-release layer.
- 18. (original) A mandrel as claimed in claim 17 wherein the electroformed structure can be removed from the substrate base by fracturing the brittle controlled-release layer.
 - 19. (withdrawn)
 - 20. (withdrawn)

21. (withdrawn)

Applicant believes that no new matter has been added with these amendments.